



MULTILAYER CERAMIC CAPACITORS

Low Profile Series

0402 to 1210 Sizes

X7R, X5R & Y5V Dielectrics

Halogen Free & RoHS Compliance



*Contents in this sheet are subject to change without prior notice.

ASC_Low Profile_(TT)_009S_AS



1. DESCRIPTION

MLCC consists of a conducting material and electrodes. To manufacture a chip-type SMT and achieve miniaturization, high density and high efficiency, ceramic condensers are used.

WTC TT series MLCC is used in product having thickness concerned generally have high capacitance and thinner product thickness. The high dielectric constant material X7R, X5R and Y5V are used for this series product.

2. FEATURES

- a. Standard size with thin thickness.
- b. Small size with high capacitance.
- c. Capacitor with lead-free termination (pure Tin).

3. APPLICATIONS

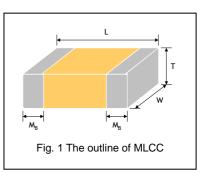
- a. For LCD panels.
- b. For PCMCA cards.
- c. For IC packaging and modules.
- d. Any thickness concerned products.

4. HOW TO ORDER

<u>11</u>	<u>15</u>	<u>X</u>	<u>475</u>	M	<u>6R3</u>	<u>C</u>	I
<u>Series</u>	<u>Size</u>	Dielectric	Capacitance	Tolerance	Rated voltage	Termination	Packaging
TT=Low profile	15 =0402 (1005)	B =X7R	Two significant	K =±10%	Two significant	C =Cu/Ni/Sn	T=7" reeled
	18 =0603 (1608)	X=X5R	digits followed by	M=±20%	digits followed by		G=13" reeled
	21 =0805 (2012)	F=Y5V	no. of zeros. And	Z =-20/+80%	no. of zeros. And		
	31 =1206 (3216)	111	R is in place of		R is in place of		
	32 =1210 (3225)		decimal point.		decimal point.		
				DA			
		8	eg.: PASSIVE SYS	TEM ALLIANCE	6R3=6.3 VDC		
		PY	$475=47 \times 10^{5}$		100=10 VDC		
		100	=4,700,000pF		160=16 VDC		
		22	=4.7µF		250=25 VDC		
		C	Ch.	9702	500=50 VDC		
			CISMIN INO	DgV	101=100 VDC		

5. EXTERNAL DIMENSIONS

Size Inch (mm)	L (mm)	W (mm)	T (mm)/Sy	mbol	M _B (mm)
0402 (1005)	1.00±0.2	0.5±0.2	0.30±0.03	L	0.25±0.10
0603 (1608)	1.6+0.15/-0.10	0.8+0.15/-0.10	0.50±0.10	Н	0.40±0.15
0805 (2012)	2.00±0.20	1.25±0.20	0.85±0.10	т	0.50±0.20
1006 (0016)	2 20 . 0 20	1 60 . 0 20	0.85±0.10	Т	0.60.0.20
1206 (3216)	3.20±0.20	1.60±0.20	1.15±0.15	J	0.60±0.20
1210 (2225)	2 20 0 20	2.50±0.20	0.85±0.10	Т	0.75 10.25
1210 (3225)	3.20±0.30	2.50±0.20	2.00±0.20	К	0.75±0.25



* Reflow soldering process only is recommended.

6. GENERAL ELECTRICAL DATA

Dielectric	X7R	X5R	Y5V		
Size					
Capacitance range*	1μF to 10μF	1µF to 10µF 0.22µF to 22µF			
Capacitance tolerance**	K (±10%	K (±10%), M (±20%)			
Rated voltage (WVDC)	10V, 16V, 25V, 50V, 100V	6.3V, 10V, 16V, 25V	10V, 16V, 25V, 50V		
Operating temperature	-55 to +125℃	-55 to +85℃	-25 to +85℃		
Capacitance characteristic		15%	+30/-80%		
Termination	Ni/Sn (lead-free termination)				

* Measured at 1.0±0.2Vrms, 1.0kHz±10%, 30~70% related humidity, 25°C ambient temperature for X7R, X5R and at 20°C for Y5V. ** Preconditioning for Class II MLCC: Perform a heat treatment at 150±10°C for 1 hour, then leave in a mbient condition for 24±2 hours

before measurement.





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7. CAPACITANCE RANGE

7-1 X7R dielectric

	Dielectric						X7R						
	Size		0805				1206				1210		
Rate	ed voltage (VDC)	10	16	25	50	10	16	25	50	10	16	100	
	1.0µF (105)							Т					
0	1.5µF (155)												
Capacitance	2.2µF (225)		Т	Т					Т			K	
ita	3.3µF (335)												
Dac	4.7µF (475)	Т						Т					
Cap	6.8µF (685)												
	10µF (106)					Т							
	22µF (226)												

7-2 X5R dielectric

	Dielectric)	(5R								
	Size		0402		06	03 0805		1206				1210						
Rate	ed voltage (VDC)	6.3	10	25	10	16	6.3	10	16	25	6.3	10	16	25	50	10	16	25
	0.22uF (224)			L	Н	Н												
	0.47uF (474)	L		L														
	1.0µF (105)	L			Н	Н		Т	Т	Т		Т	Т	Т				
9	1.5µF (155)							Т	Т			Т	Т	Т				
ano	2.2µF (225)	L					T	T	T	Т		Т	Т	Т	Т			
cit	3.3µF (335)						EL T		13	Ŧ		Т	Т	Т		Т		
Capacitance	4.7µF (475)	L			Н	132		Ť	- 7 <u>R</u>	7 <u>.</u>	/	Т	Т	Т		Т		
ü	6.8µF (685)					1 REE	"Lt	阳イ	$2 \times$									
	10µF (106)				K	\leq	(イン		210	12.	5	J/T		Т		Т		Т
	22uF (226)				1. tivo	1.1	Ť	Т		1/2	J.	X	Т				Т	
	47uF (476)				rnu	4	p.			\mathbb{N}	\geq	12						

7-3 Y5V dielectric

	Dielectric						Y5V					
	Size		0	305			12	06		12	1210	
Rate	ed voltage (VDC)	10	16	25	50	10	16	25	50	10	16	
	1.0µF (105)			72 7	Т			12				
0	1.5µF (155)			CIA	6							
DC.	2.2µF (225)		Т	Alco	Schn	alatai		Т				
ita	3.3µF (335)	Т		-2/1/	Thomas	01051	- MI HAY					
Dac	4.7µF (475)	Т	Т		ECHNNIN	CV ATODAR	AUN4.					
Capacitance	6.8µF (685)				.010	or como						
5	10µF (106)	Т				Т				Т		
	22µF (226)											

8. PACKAGING STYLE AND QUANTITY

Size	Thickness May (mm)/Cumbol	7" reel			
Size	Thickness Max (mm	<i>j</i> /Symbol	Paper tape	Plastic tape		
0402 (1005)	0.33	L	15k	-		
0603 (1608)	0.60	Н	4k	-		
0805 (2012)	0.95	Т	4k	-		
4000 (0040)	0.95	Т	4k	-		
1206 (3216)	1.30	J	-	3k		
1210 (3225)	0.95	Т	-	3k		
1210 (3225)	2.00	К	-	1k		

Unit: pieces





Sep. 2021

9. RELIABILITY TEST CONDITIONS AND REQUIREMENTS

No.	Item	Test Condition		Requirements
1.	Visual and			narkable defect.
	Mechanical		* Dimens	sions to conform to individual specification sheet.
2.	Capacitance	* Test temp.: Room Temperature.	* Shall n	ot exceed the limits given in the detailed spec.
3.	Q/ D.F.	Cap≤10µF, 1.0±0.2Vrms, 1kHz±10%	X7R/X5F	
υ.		Cap>10µF, 0.5±0.2Vrms, 120Hz±20%** ** Test condition: 0.5±0.2Vrms,1KHz±10%	Rated	
	(Dissipation	TT18X \geq 475(10V), TT15X series	100V	≤5% 25V, 16V, 10V ≤10%
	Factor)		6.3V	≤15%
		*Before initial measurement (Class II only): To apply	e-aging Y5V:	
		at 150 $^{\circ}$ for 1hr then set for 24±2 hrs at room temp .	Rated	l vol. D.F.
			50V	≤7%
			25V 16V/1	≤9% 0V ≤12.5%
4		* To apply voltage: 250% rated voltage.		
4.	Dielectric	* Duration: 1 to 5 sec.	* No evic	dence of damage or flash over during test.
	Strength	* Charge and discharge current less than 50mA.		
5.	Insulation	* Test temp.: Room Temperature.	≥10GΩ o	or RxC≥100Ω-F whichever is smaller.
	Resistance	* To apply rated voltage for max. 120 sec.		
6.		With no electrical load.		
0.	remperature	T.C. Operating Temp	ТО	Canacitanas Change
	Coefficient	X7R -55~125°C at 25°C	T.C.	Capacitance Change Within ±15%
		X5R -55~85°C at 25°C Y5V -25~85°C at 20°C	X7R X5R	
		*Before initial measurement (Class II only):	Y5V	Within ±15%
		To apply de-aging at 150℃ for 1hr then set for 24±2	rs at	Within +30%/-80%
		0402 0603		2
		Cap<1µF: 1V Cap<1µF: 1V		21
		Cap=1µF: 0.5V*		C/
		0402B474-10V: 0.5V 0402B224-16V: 0.5V 1µF≤Cap≤4.7µF: 0.5V	- "F-	- 79
		0402X475M6R3: 0.5V		
		1μF <cap<10μf: 0.2v<br="">Cap>4.7μF: 0.2V</cap<10μf:>		
		*0402B105M6R3V: 0.2V Cap≥10μF: 0.2V		
		0805 1206/1210	ALLIANCE	
		Cap<10µF: 1V Cap≤10µF: 1V		
		Cap=10µF: 0.5V 10µF <cap≤100µf: 0.5<="" td=""><td></td><td>2 底</td></cap≤100µf:>		2 底
		0805B475/6.3V~25V: 0.5V	_	
		room temp.		
-		* Pressurizing force : 5N (≤0603) and 10N (>0603)		010
7.	Adhesive	* Test time: 10±1 sec.	No rem	narkable damage or removal of the terminations.
	Strength of	ECHNOLOG	CODD TION.	
	Termination		OKPUKALIS	
8.	Vibration	* Vibration frequency: 10~55 Hz/min.	* No rem	narkable damage.
	Resistance	 Total amplitude: 1.5mm * Test time: 6 hrs. (Two hrs each in three mutually 	* Cap ch	nange and Q/D.F.: To meet initial spec.
		perpendicular directions.)		
		* Before initial measurement (Class II only):		
		To apply de-aging at 150℃ for 1hr then set for 24±2	rs at	
		room temp. * Cap./DF(Q) Measurement to be made after de-agi	. at	
		150° for 1hr then set for 24±2 hrs at room temp.		
9.	Solderability	* Solder temperature: 235±5℃	95% mir	n. coverage of all metalized area.
	,,	* Dipping time: 2±0.5 sec.		
10.	Bending Test	* The middle part of substrate shall be pressurized t		narkable damage.
		of the pressurizing rod at a rate of about 1 mm per s the deflection becomes 1 mm and then the pressure	er (Can ch	nange :
		maintained for 5±1 sec.		5R: within ±12.5%
		* Before initial measurement (Class II only):	Y5V w	ithin ±30%
		To apply de-aging at 150 $^{\circ}$ C for 1hr then set for 24±2	re of	pacitance change means the change of capacitance under
		room temp.	specified	d flexure of substrate from the capacitance measured befor
		* Measurement to be made after keeping at room te 24±2 hrs.	p. for the test.))
11	Decister		* * *	
11.	Resistance to	* Solder temperature: 260±5℃		narkable damage.
11.	Resistance to Soldering Heat		* Can ch	-
11.		* Solder temperature: 260±5℃ * Dipping time: 10±1 sec	se the * Cap ch	-
11.		* Solder temperature: 260±5℃ * Dipping time: 10±1 sec * Preheating: 120 to 150℃ for 1 minute before imme capacitor in a eutectic solder. *Before initial measurement (Class II only): To apply	se the * Cap ch X7R/X	hange:
11.		* Solder temperature: 260±5℃ * Dipping time: 10±1 sec * Preheating: 120 to 150℃ for 1 minute before imme capacitor in a eutectic solder.	se the * Cap ch X7R/X e-aging Y5V: w * O/D F	hange: 5R: within ±7.5%

ASC_Low Profile_(TT)_009S_AS

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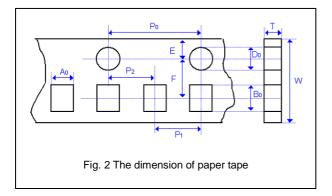


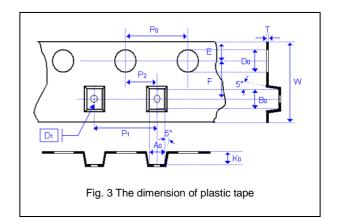
No.	Item		Test Condition			Requireme	nts
12.	Temperature	* Conduc	t the five cycles according to the	e temperatures and	* No remarkable d	lamage.	
	Cycle	time.			* Cap change :		
	-	Step	Temp. (℃)	Time (min.)	X7R/X5R: within	ו ±7.5%	
		1	Min. operating temp. +0/-3	30±3	Y5V: within ±20°	%	
		2	Room temp.	2~3	* Q/D.F., I.R. and	dielectric strength: To	meet initial requirements.
		3	Max. operating temp. +3/-0	30±3		g	·····
		4	Room temp.	2~3			
		* Before i	nitial measurement (Class II only	y): To apply de-aging			
		at 150℃ i	or 1hr then set for 24±2 hrs at ro	oom temp.			
		* Cap. / D	F(Q) / I.R. Measurement to be r	made after de-aging			
		at 150℃ i	or 1hr then set for 24±2 hrs at ro	oom temp.			
13.	Humidity	* Test ten	np.: 40±2℃		*No remarkable d	amage. (7R/X5R: within ±25%	
	(Damp Heat)	* Humidit	y: 90~95% RH			'5V: within ±30%; 6.3\	
	Steady State	* Test tim	e: 500+24/-0hrs.		*Q/D.F. value:		
		* Before i	nitial measurement (Class II only	y): To apply de-aging	X7R/X5R:		-
			or 1hr then set for 24±2 hrs at ro	•	Rated vol.	D.F.	-
		* Cap. / D	PF(Q) / I.R. Measurement to be r	made after de-aging	100V	≤7.5%	-
		at 150℃ I	or 1hr then set for 24±2 hrs at ro	oom temp.	25V, 16V	≤15% <20%	-
					10V 50V, 6.3V	≤20% ≤30%	-
					Y5V:	<u>≤30%</u>	
				15	Rated vol.	D.F.	1
			14 1	所月 1	50V	≤10%	
				1 IL /1	25V	≤15%	-
			1X4 The	、话版份,	16V, 10V	≤20%	_
			ty X	X		≥10 Ω-F whichever is s	- maller
14	Humidity	* Test ten	np.: 40±2℃		*No remarkable d		
	(Damp Heat)		y: 90~95%RH			7R/X5R: within ±25%	(within + 20/ 40%
	Load					′5V: within ±30%; 6.3∖	/, within +30/-40%
	Loau	1	e: 500+24/-0 hrs.		*Q/D.F. value:		
			v voltage : Rated voltage.	SIVE SYSTEM AL	¹ X7R/X5R:		-
			or 1hr then set for 24±2 hrs at ro	.,	Rated vol.	D.F.	
			F(Q) / I.R. Measurement to be r		100V	≤7.5%	_
		1	for 1hr then set for 24±2 hrs at		25V, 16V	≤15%	_
		at 100 0		Sol	10V	≤20%	_
			"HISINI T	<i>Concord</i>	50V, 6.3V	≤30%	
				HAIDLOOD	Y5V: Rated vol.	D.F.	1
				HNOLOGY CORPOR	50V		-
					25V	≤15%	-
					16V, 10V	≤13 <i>%</i> ≤20%	1
						RxC≧5 Ω-F whichever	⊣ is smaller
15	High	* Test tem	p. :		*No remarkable da		
13.			R/X7E: 125±3℃			amage. 7R/X5R: within ±25%	
	Temperature		V: 85±3℃		Y	′5V: within ±30%; 6.3∖	/, within +30/-40%
	Load	-	e: 1000+24/-0 hrs. / voltage: 150% of rated voltage.		*Q/D.F. value:		
	(Endurance)		f rated voltage for below range.	•	X7R/X5R:		_
		Size	Dioloctric Rated	Capacitance	Rated vol.	D.F.	
			voltage	range	100V	≤7.5%	_
		TT15 TT18	X5R 6.3V Y5V 6.3V,10V	<u>C≧1.0µF</u> C≧2.2µF	25V, 16V	≤15%	4
			Y5V 6.3V	C≧2.2µF C≧10µF	10V	≤20%	_
		TT21	X5R/X7R/X6S ≦10V	C≧10µF	50V, 6.3V	≤30%	
			Y5V 6.3V	C≧22µF	Y5V:		-
		*Before ir	nitial measurement (Class II only): To apply de-aging	Rated vol.	D.F.	_
			for 1hr then set for 24±2 hrs at ro	, ,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	50V	≤10%	4
			F(Q) / I.R. Measurement to ©r d	le-aging at 150℃ for	25V	≤15%	_
		1hr then	set for 24±2 hrs at room temp.		16V, 10V	≤20%	
		1			*I.R.: 1GΩ or RxC≧	≧10 Ω-F whichever is s	maller.

* "Room condition" Temperature: 15 to 35°C, Relative humidity: 25 to 75%, Atmospheric pressure: 86 to 106kPa.

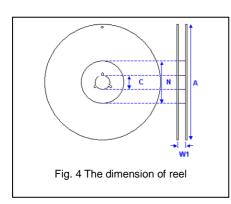
APPENDIXES

■ Tape & reel dimensions





Size	0402	0603	0805	12	206	12	10
Thickness	L	н	Т	Т	J	Т	к
A	0.70 +/-0.20	1.05 +/-0.30	1.50 +/-0.20	1.90 +/-0.50	< 2.00	< 3.05	< 3.05
B ₀	1.20 +/-0.20	1.80 +/-0.30	2.30 +/-0.20	3.50 +/-0.50	< 3.70	< 3.80	< 3.80
т	≦0.80	≦1.20	≦1.20	≦1.20	0.23 +/-0.1	0.23 +/-0.1	0.23 +/-0.1
Ko	-	1774	- -		< 2.00	< 1.50	< 2.50
w	8.00 +/-0.30	8.00 +/-0.30	-8.00 +/-0.30	8.00+/-0.30	8.00 +/-0.30	8.00 +/-0.30	8.00 +/-0.30
Po	4.00 +/-0.10	4.00 +/-0.10	PASS 4.00 +/-0.10	ALL 14.00 = +/-0.10	4.00 +/-0.10	4.00 +/-0.10	4.00 +/-0.10
10xP₀	40.00 +/-0.10	40.00 +/-0.20	40.00 +/-0.20	40.00 +/-0.20	40.00 +/-0.20	40.00 +/-0.20	40.00 +/-0.20
P ₁	2.00 +/-0.05	4.00 +/-0.10	4.00 +/-0.10	4.00 +/-0.10	4.00 +/-0.10	4.00 +/-0.10	4.00 +/-0.10
P ₂	2.00 +/-0.05	2.00 +/-0.05	2.00	2.00 +/-0.05	2.00 +/-0.05	2.00 +/-0.05	2.00 +/-0.05
Do	1.50 +0.1/-0	1.50 +0.1/-0	1.50 +0.1/-0 _V	1.50 +0.1/-0	1.50 +0.1/-0	1.50 +0.1/-0	1.50 +0.1/-0
D ₁	-	-		-	1.00 +/-0.10	1.00 +/-0.10	1.00 +/-0.10
E	1.75 +/-0.10	1.75 +/-0.10	1.75 +/-0.10	1.75 +/-0.10	1.75 +/-0.10	1.75 +/-0.10	1.75 +/-0.10
F	3.50 +/-0.05	3.50 +/-0.05	3.50 +/-0.05	3.50 +/-0.05	3.50 +/-0.05	3.50 +/-0.05	3.50 +/-0.05



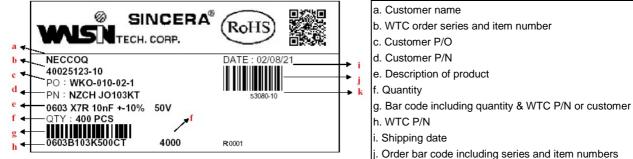
Size	0402, 0603, 0805, 1206, 1210						
Reel size	7"	10"	13"				
С	13.0±0.5	13.0±0.5	13.0±0.5				
W 1	10.0±1.5	10.0±1.5	10.0±1.5				
Α	178.0±2.0	250.0±2.0	330.0±2.0				
N	N 60.0+1.0/-0		50 min				

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Example of customer label





*Customized label is available upon request

- k. Serial number of label

Constructions

No.	Nan	ne	X7R, X5R, Y5V		
1	Ceramic	material	BaTiO ₃ based		
2	Inner ele	ectrode	NIL (1)	- 1	
3		Inner layer	Cu	t,a	
4	Termination	Middle layer	Ni	2 Zr	
5		Outer layer	Sn (Matt)		Fig. 5 The construction of MLCC
			PASSIVE SYSTEM ALLIANCE		a

Storage and handling conditions

- (1) To store products at 5 to 40°C ambient temperature and 20 to 70%. related humidity conditions; MSL Level 1.
- (2) The product is recommended to be used within one year after shipment. Check solderability in case of shelf life extension is needed.

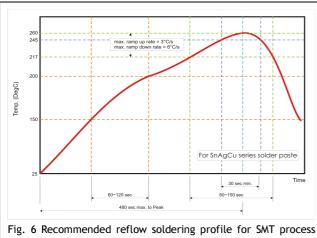
Cautions:

- a. The corrosive gas reacts on the terminal electrodes of capacitors, and results in the poor solderability. Do not store the capacitors in the ambience of corrosive gas (e.g., hydrogen sulfide, sulfur dioxide, chlorine, ammonia gas etc.)
- b. In corrosive atmosphere, solderability might be degraded, and silver migration might occur to cause low reliability.
- c. Due to the dewing by rapid humidity change, or the photochemical change of the terminal electrode by direct sunlight, the solderability and electrical performance may deteriorate. Do not store capacitors under direct sunlight or dewing condition. To store products on the shelf and avoid exposure to moisture.



Recommended soldering conditions

The lead-free termination MLCCs are not only to be used on SMT against lead-free solder paste, but also suitable against lead-containing solder paste. If the optimized solder joint is requested, increasing soldering time, temperature and concentration of N₂ within oven are recommended.



with SnAgCu series solder paste.

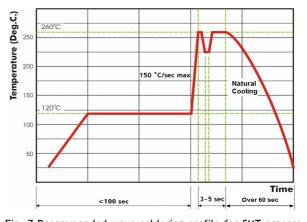


Fig. 7 Recommended wave soldering profile for SMT process with SnAgCu series solder.

